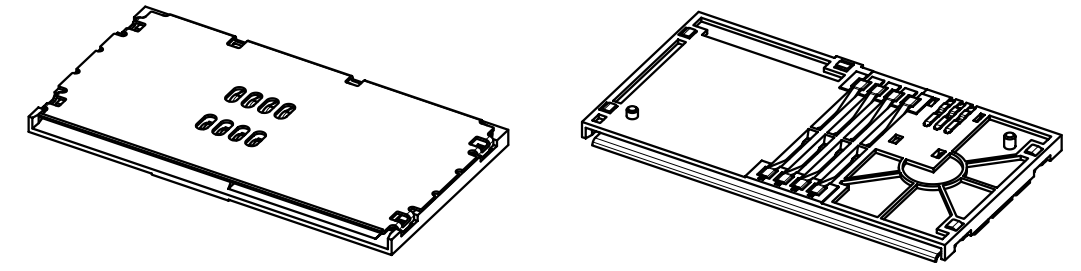
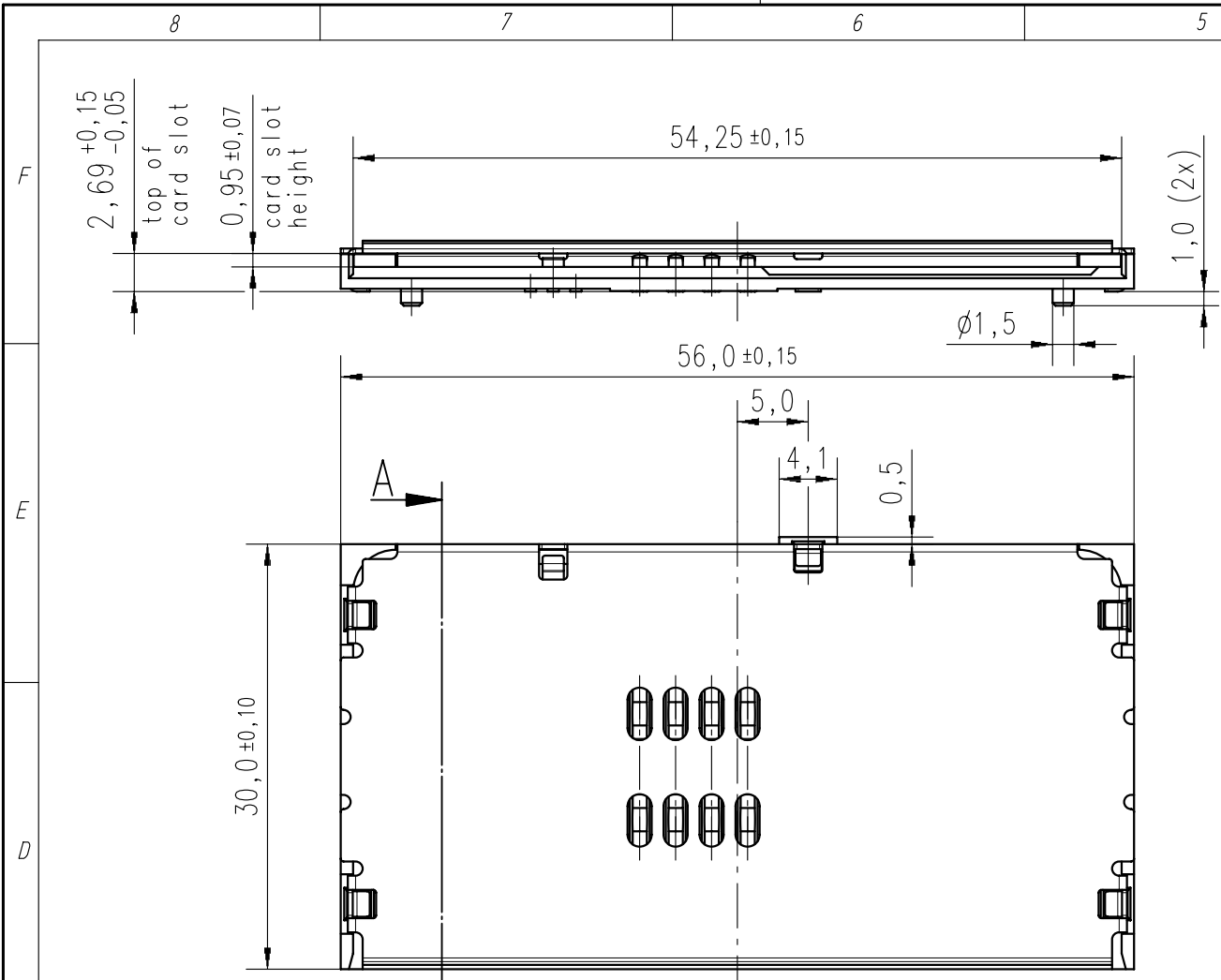
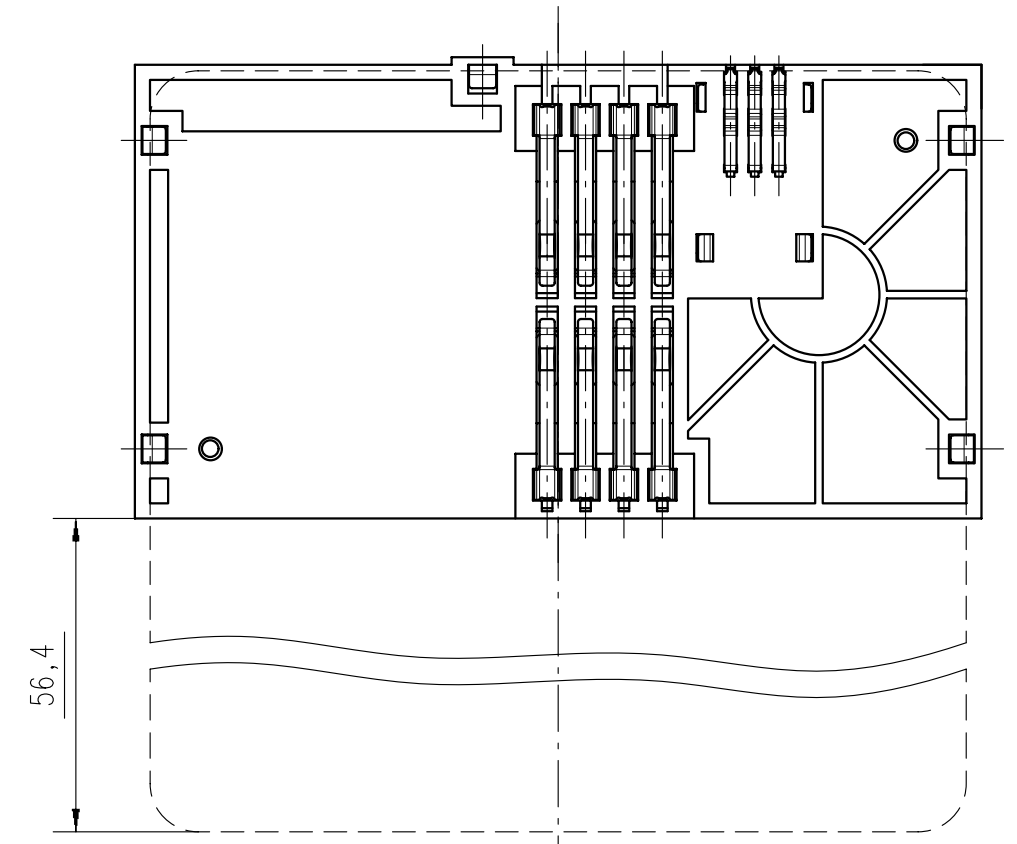
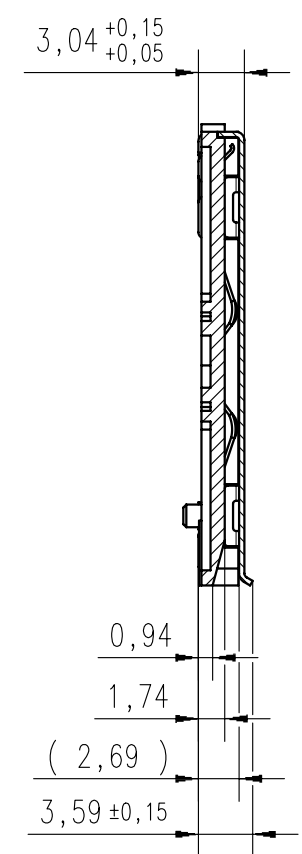


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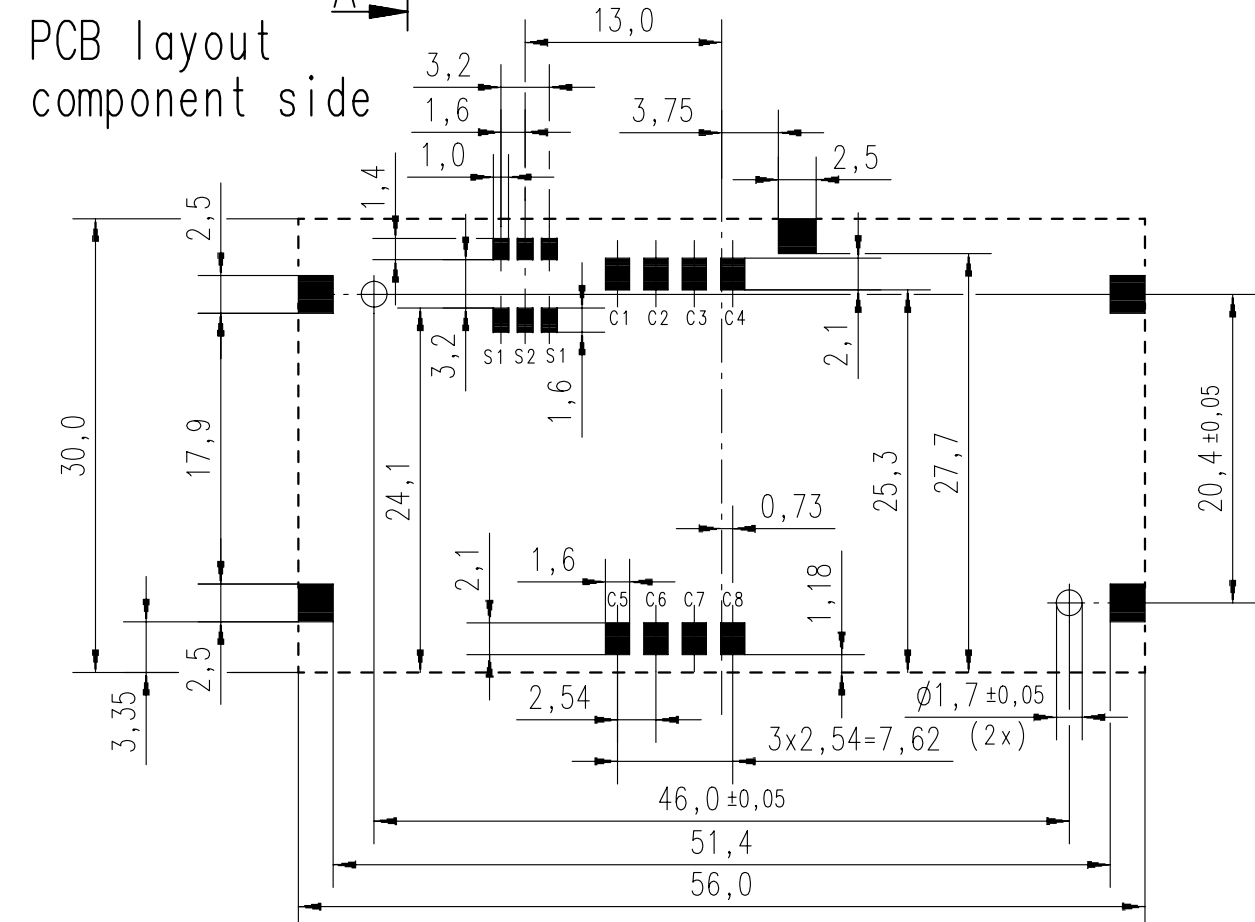
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A-A



PCB layout component side



co-planarity of solder pins $\square 0,15$ ⁰²
 recommended thickness of solderpaste min. 0,15 mm
 reflow solder profile see sheet 2



Im ungelöteten Zustand keine Karte stecken ⁰²
 Don't insert a card in unsoldered condition

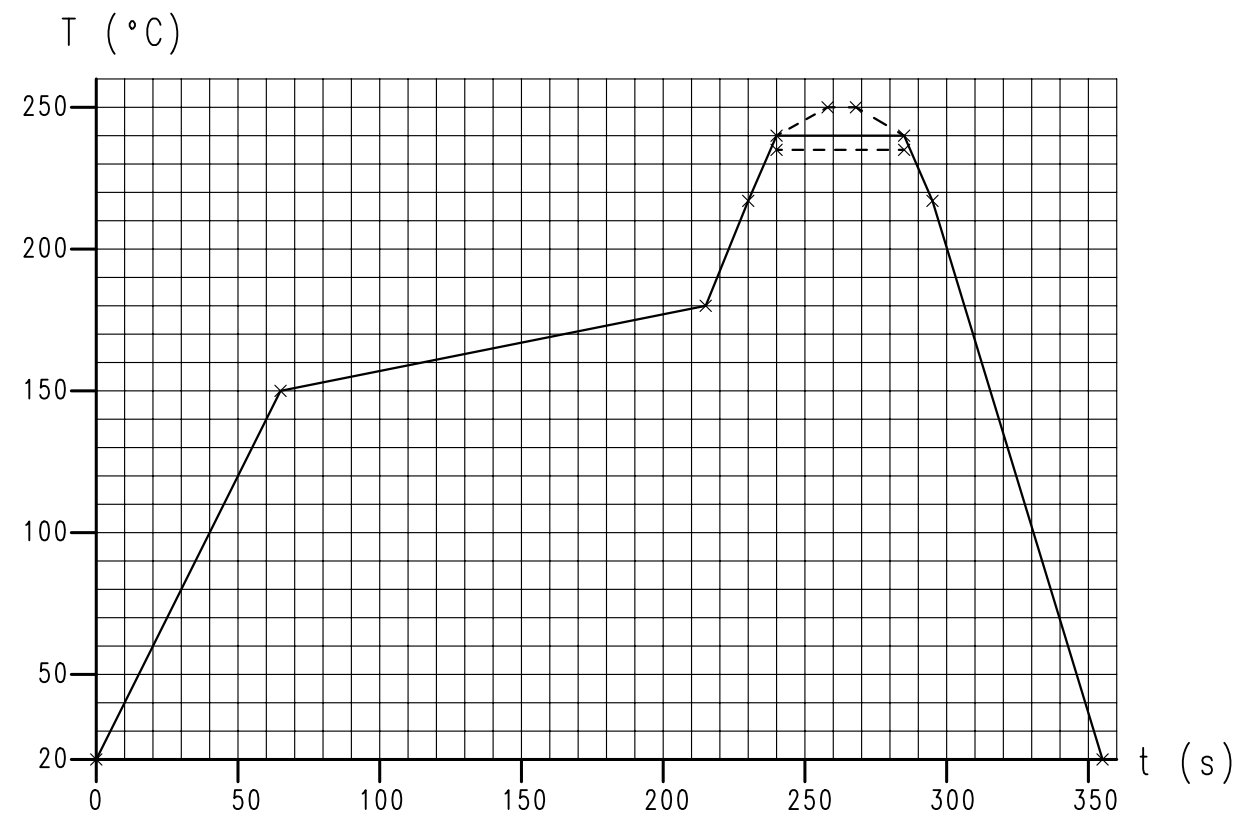
Gewicht (errechnet) / Calc WT: 7,8 9		Zul. Abw./Tolerances:		Maßstab/Scale 2:1		A3	
Prüfmaß/Testdimension		ISO 2768-mH		DIN 6784		CUSTOMER DRAWING	
Teileindex Partindexnumber		06		Datum/Date		Name	
		Gez.		20.09.		Bertsch	
		Drawn					
		Gepr.					
		Checked					
		Amphenol-Tuchel					
		Electronics GmbH					
02 200700425 21.06.07 Ber.		M		C702 10M008 252 40		Blatt/Sheet 1	
01 200600185 20.09.06 Ber.						2 Bl.	
Index Änderung/Description Datum/Date Name		Ers. f./Similar to:					

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temperature profile for lead free soldering ⁰²

Sn (3,0-4,0)Ag (0,5-0,9)Cu solder alloy
 temperature measured on solderable termination



Parameter	Specification
Average temperature gradient in preheating	2,5 °C/s
Preheating temperature	150 °C - 200 °C
Soak time	120 s - 180 s
Time above 217 °C	40 s - 120 s
Peak temperature in reflow	235 °C - 250 °C
Time at peak temperature	10 s - 50 s
Temperature gradient in cooling	max -5 °C/s

Specification ⁰²

- DESIGN**
 type: push-pull, wiping contacts
 normally open switch
 with positioning studs
- GENERAL CHARACTERISTICS**
 number of contacts: 8 contacts
 switch: normally open (no card inserted)
 card type: according to ISO 7810 / 7816
 card thickness: 0,76 ±0,08 mm
 termination: SMT
- MATERIALS AND PLATING**
 insulator: LCP, black
 contact plating: Au over Ni
- CLIMATIC CHARACTERISTICS**
 operating temperature: -25 °C to +70 °C
 storage temperature: -40 °C to +85 °C
 soldering process: reflow soldering
- ELECTRICAL CHARACTERISTICS**
 contact resistance: max. 100 mΩ (data contacts)
 max. 1 Ω (switch)
 insulation resistance: >10⁹ Ω
 high voltage resistance: 500 V AC for 1 minute
 rated voltage: <15 V DC
 rated current: <1 A
- MECHANICAL CHARACTERISTICS**
 card insertion force: <10 N
 card extraction force: >1 N
 mechanical lifetime: 100.000 mating cycles
 (without corrosion stress)
- PACKAGING**
 packaging: 32 parts per tray
 24 trays per carton

Gewicht (errechnet) / Calc WT: 7,8 g		Zul. Abw. / Tolerances:		Maßstab / Scale 2:1		A3			
Prüfmaß / Testdimension		ISO 2768-mH				CUSTOMER DRAWING			
Teileindex / Part index number		06		Datum / Date		Name		Smart Card Connector	
		Gez.		20.09.		Bertsch		SMT with normally open switch	
		Drawn							
		Gepr.							
		Checked							
02 200700425 21.06.07 Ber.		Amphenol-Tuchel		M		C702 10M008 252 40		Blatt / Sheet 2	
01 200600185 20.09.06 Ber.		Electronics GmbH						2 Bl.	
Index Änderung / Description Datum / Date Name				Ers. f. / Similar to:					